

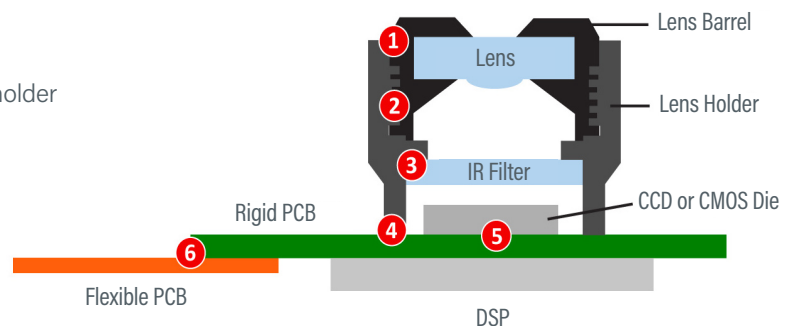
Light-Curable Materials for Camera Module Assembly









- Excellent adhesion to commonly used substrates in camera module assemblies
- Materials cure in seconds allowing faster processing and higher throughput
- Materials available for a variety of applications including active alignment, barrel fixturing, and FPC reinforcement
- Good resistance to moisture and shock

Dymax light-curable adhesives are ideal for use in the assembly of camera modules used in smart connected devices, automobiles, and industrial camera systems. Our adhesives cure in seconds, providing greater product yields in a much shorter assembly time. They provide excellent adhesion to substrates typically used in the manufacture of camera modules and electronic device housings, and can withstand harsh conditions like the moisture and shock which electronic devices are often exposed to.

Typical Camera Module Applications

- 1 - Bonding the camera lens
- 2 - Fixturing the camera lens barrel to the lens holder
- 3 - Bonding the IR filter to the lens holder
- 4 - Bonding the lens holder to the PCB
- 5 - Attaching the CCD or CMOS die to the PCB
- 6 - Reinforcing the FPC



Product Number	Features	Viscosity, cP	Durometer Hardness	Tensile at Break, MPa [psi]	Modulus of Elasticity, MPa [psi]	Halogen Free?
Fixturing the Camera Lens Barrel to the Lens Holder Typical requirement: Tack-free surface						
3094-T-REV-A	UV/Visible light cure; fast curing; low shrinkage and stress	11,750	D65	12.4 [1,800]	179 [26,000]	
9803	Very low shrinkage epoxy; UV/Visible light cure; LED curable; low temp. heat cure (80-85°C); moisture & thermal cycle resistant; low water absorption; cold storage/ship	86,000	D94	36.7 [5,328]	3,983 [578,000]	Not Tested
9801	Low shrinkage epoxy; UV/Visible light cure; LED curable; low temp. heat cure (80-85°C); moisture & thermal cycle resistant; low water absorption; cold storage/ship	60,000	D90	45 [6,600]	1,600 [230,600]	Not Tested
Flexible PCB Reinforcement Typical requirement: Flexibility; bend resistance						
9101	UV/Visible light cure with secondary moisture cure; flexible; moisture and thermal resistant	7,000	D30-D50	5.06 [735]	175 [2,550]	
9008	UV/Visible light cure; remains flexible to -40°C; moisture resistant	4,500	D35	10 [1,500]	45 [6,500]	
Other Applications						
6-621-GEL	UV/Visible light cure with secondary heat cure; activator cure; hard, clear bonds	25,000	D80	28 [4,000]	730 [106,000]	
9309-SC	UV/Visible light cure; adhesion to various PCB substrates; formulated with See-Cure color-change technology	45,000	D57	22 [3,200]	163 [23,800]	
9483-Z	UV/Visible light-cure with secondary moisture cure; excellent chemical and thermal shock resistance; blue fluorescing	750	D60	10.3 [1,500]	480 [70,000]	
6-621-T	UV/Visible light cure with secondary heat cure; activator cure; hard, clear bonds	3,500	D80	28 [4,000]	730 [106,000]	
9001-E-V3.0	UV/Visible light cure; low ionic; good electrical properties	400	D45	5.17 [750]	17.2 [2,500]	

 Featured Product